

OVERVIEW

The LC65102A and LC65104A are 4-bit, single-chip microprocessors that incorporate 2 Kbyte ROM and 128×4 -bit RAM, and 4 Kbyte ROM and 256×4 -bit RAM, respectively, making them ideal for timer controllers, audiovisual equipment and domestic appliances.

The LC65102A and LC65104A comprise one 2-bit and five 4-bit bidirectional I/O ports, a three-wire serial interface, an eight-channel, 8-bit A/D converter and a 14-bit D/A converter that can be configured as separate 6-bit and 8-bit modules or as a single 14-bit module. An on-chip oscillator can be directly connected to either an external crystal or ceramic resonator, or alternatively, an external oscillator can be used.

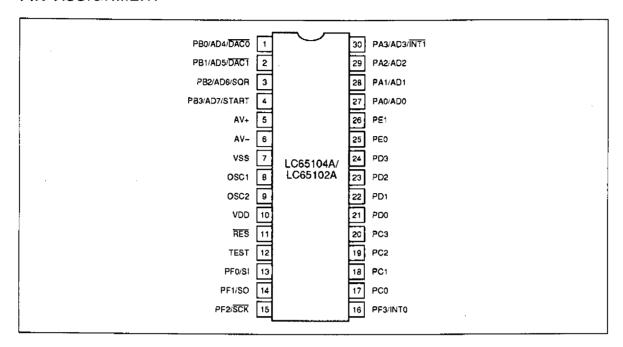
The mask options for the LC65102A and LC65104A comprise a 14-bit general-purpose timer, used to generate pulsewidth modulated output or tone output, a 14-bit clock or overrun watchdog timer, and an AC zero-crossing detector or Schmitt trigger input circuit. Two power-saving standby modes are also provided.

The LC65102A and LC65104A operate over a 2.7 to 6.0 V supply range and are available in 30-pin SDIPs. A 30-pin SMFP is currently under development.

FEATURES

- 77 instructions
- On-chip 2 Kbyte ROM and 128 × 4-bit RAM (LC65102A) and 4 Kbyte ROM and 256 × 4-bit RAM (LC65104A)
- 0.92 μs (4.33 MHz clock and $V_{DD} \ge 4.5$ V) or 1.84 μs (2.17 MHz clock and $V_{DD} \ge 4.0$ V) minimum instruction cycle times
- · Software-selectable system clock
- · Four banks of eight working registers and 16 flags
- · Eight-level stack
- 22 bidirectional I/O lines, including 12 multiplexed lines
- 8-bit precision, eight-channel tracking A/D converter
- 8-bit interval timer for PWM D/A converter and music generator
- 14-bit timer for calendar/clock function
- Separate 6-bit and 8-bit or single 14-bit D/A converter configurations
- Serial I/O interface
- AC zero-crossing detector mask option
- · Two external interrupts, two timer interrupts and one serial I/O interrupt
- Wait function allows oscillator to stabilize after reset
- On-chip oscillator supports 4.19 MHz crystal, 400 kHz or 4.0 MHz ceramic resonators
- LC65999 evaluation chip, EVA800/850 emulator, TB65XXX adapter board and LC65PG10X piggy-back connector evaluation tools available
- · HALT/HOLD standby functions
- 2.7 to 6.0 V supply operating range
- 30-pin SDIP and 30-pin SMFP (under development)

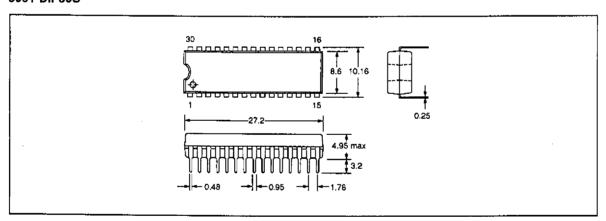
PIN ASSIGNMENT



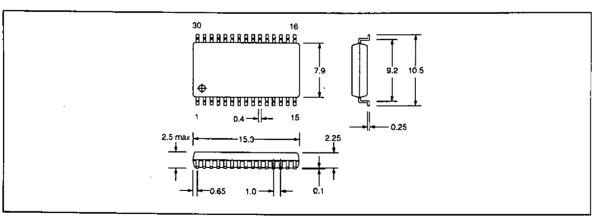
PACKAGE DIMENSIONS

Unit: mm

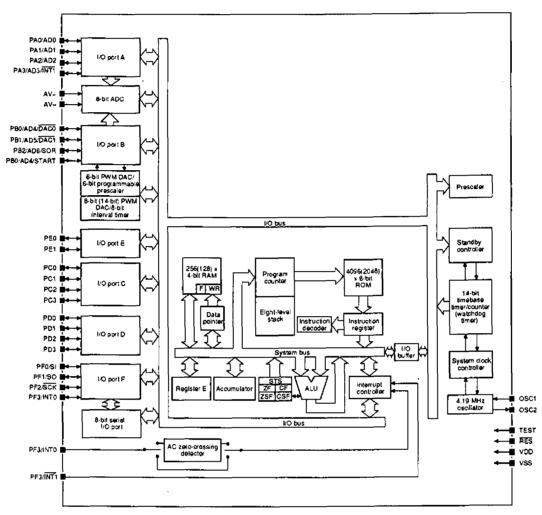
3061-DIP30S



3073A-MFP30S



BLOCK DIAGRAM



Note Values in parentheses indicate LC65102A RAM and ROM capacities

PIN DESCRIPTION

Number	Name	Description
1	PB0/AD4/DAC0	
2	PB1/AD5/DAC1	4-bit I/O port B multiplexed with A/D converter lines AD4 to AD7, D/A lines DACO
3	PB2/AD6/SQR	
4	PB3/AD7/START	1
5	AV+	
6	AV-	A/D converter reference voltage input
7	VSS	Ground
8	0801	External crystal or ceramic resonator connection or external clock input
9	0802	External crystal or ceramic resonator connection
10	VDD	5 V supply
11	RES	System reset input. Normally HIGH
12	TEST	Test pin. Normally LOW

Number	Name	Description
13	PF0/SI	
14	PF1/SO	4-bit I/O port F multiplexed with serial input and output lines SI and SO, serial
15	PF2/SCK	clock output SCK and interrupt request input INTO. Normally HIGH
16	PF3/INTO	
17	PCO	
18	PC1	4 his 1/2 2
19	PC2	-4-bit I/O port C
20	PC3	
21	PD0	
22	PD1	A hit 1/0 part B
23	PD2	4-bit I/O port D
24	PD3	
25	PEO	O his 1/O and E. Alamadh, HICH
26	PE1	- 2-bit I/O port E. Normally HIGH
27	PA0/AD0	
28	PA1/AD1	4-bit I/O port A multiplexed with A/D converter input lines ADO to AD3 and
29	PA2/AD2	interrupt input INT1. Normally HIGH
30	PA3/AD3/INT1	1

SPECIFICATIONS

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage range	V _{DD}	-0.3 to 7.0	V
TEST, RES and OSC1 input voltage range	V _{I1}	-0.3 to V _{DD} + 0.3	v
AV * input voltage range	V ₁₂	-0.3 to V _{DD} + 0.3	٧
AV input voltage range	Vı3	-0.3 to $V_{DD} + 0.3$	V
Ports A, B and F3 input/output voltage range	Viot	-0.3 to V _{DD} + 0.3	V
Ports C, D and E, and F0 to F2 input/output voltage range (open-drain output)	V ₁₀₂	-0.3 to 15.0	V
Ports C, D and E, and FO to F2 input/output voltage range (totem-pole output)	V _{IO3}	-0.3 to V _{DD} + 0.3	٧
Ports A, B, E and F peak output current range	l _{OP1}	-2 to 10	mA
Ports C and D peak output current range	I _{OP2}	-2 to 20	mA
Ports A, B, E and F average output current per pin range	l _{OA1}	-2 to 10	mA
Ports C and D average output current per pin range	I _{OA2}	-2 to 20	mA
Ports A, B, E and F average current per port range	ΣΙΟΑ1	-24 to 120	mA
Ports C and D average current per port range	Σl _{0A2}	-20 to 100	mA

Parameter	Symbol	Rating	Unit
30-pin DIP power dissipation	Po	400	mW
30-pin MFP power dissipation	PD	200	mW
Operating temperature range	Topg	-40 to 85	deg. C
Storage temperature range	T _{stg}	-55 to 125	deg. C

Recommended Operating Conditions

 $V_{SS} = 0 V$, $T_n = 25 deg$. C

Parameter	Symbol	Rating	Unit
Supply voltage	V _{DD}	5	٧
Supply voltage range	Voo	2.7 to 6.0	v

Electrical Characteristics

 V_{DD} = 2.7 to 6.0 V, V_{SS} = 0 V, T_a = -40 to 85 deg. C unless noted otherwise

Parameter	Symbol	Odialo	Rating			Unit
Parameter .		Condition	min	typ	max	Unit
	V _{DD1}	0.92 μs ≤ t _{cyc} < 36 μs	4.5	-	6.0	V
Supply voltage	V _{D02}	1.84 µs ≤ t _{cyc} < 36 µs	4.0	_	6.0	٧
	V _{DD3}	9.8 μs ≤ t _{cyc} < 36 μs	2.7	-	6.0	٧
Standby supply voltage	Vst		1.8	_	6.0	٧
Port E and FO to F2 HIGH-level input voltage (open-drain output)	ViH1	n-channel transistor OFF	0.80V _{DD}		13.5	٧
Port E and FO to F2 HIGH-level nput voltage (totem-pole output)	V _{iH2}	n-channel transistor OFF	0.80V _{DD}	-	Voo	٧
Ports A and B HtGH-level input voltage	ViH3	n-channel transistor OFF	1.9	_	V _{DD}	٧
Ports C and D HIGH-level input	V _{IH4}	n-channel transistor OFF, V _{DD} = 4.5 to 6.0 V	0.70V _{DD}	_	13.5	٧
		n-channel transistor OFF	0.75V _{DD}		13.5	٧
Ports C and D HIGH-level input voltage (totem-pole output)	V _{IH5}	n-channel transistor OFF, V _{DD} = 4.5 to 6.0 V	0.70V _{DD}	_	V _{DD}	٧
		n-channel transistor OFF	0.75V _{DD}	_	V _{DD}	٧
OSC1, START, PF3/INTO and INT1 HIGH-level input voltage. See note 1.	VIH6	n-channel transistor OFF, external oscillator input. See figure 16.	0.80V _{DD}	_	Voo	٧
RES HIGH-level input voltage		$V_{DD} = 4.5 \text{ to } 6.0 \text{ V}$	0.80V _{DD}		V _{DD}	٧
The member input voltage	V_{1H7}	$V_{DD} = 1.8 \text{ to } 6.0 \text{ V}$	0.85V _{DD}		V _{DD}	٧
Port E and F0 to F2 LOW-level	V _{IL1}	n-channel transistor OFF, V _{DD} = 4.5 to 6.0 V	Vss	_	0.20V _{DD}	٧
input voltage	¥1 <u>C</u> 1	n-channel transistor OFF	Vss	-	0.15V _{DD}	٧
Ports A and B LOW-level input	V _{IL2}	n-channel transistor OFF, V _{DD} = 4.5 to 6.0 V	Vss	_	0.5	٧
voltage	• ILZ	n-channel transistor OFF	Vss	_	0.35	V

LC65102A, LC65104A

Parameter	Symbol	Condition		Unit		
Latamoloj	oyanaor		min	typ	max	
Ports C and D LOW-level input	Vila	n-channel transistor OFF, V ₀₀ = 4.5 to 6.0 V	Vss	-	0.30V _{DD}	٧
voltage	•	n-channel transistor OFF	Vss	_	0.25V _{DD}	V
CTART LOW level input walkers	17	$V_{DD} = 4.5 \text{ to } 6.0 \text{ V}$	Vss	_	0.20V _{DD}	٧
START. LOW-level input voltage	V _{IL4}	$V_{DD} = 1.8 \text{ to } 6.0 \text{ V}$	Vss	_	0.15V _{DD}	V
OSC1, RES, PF3/INTO and INT1 LOW-level input voltage. See	V _{IL5}	n-channel transistor OFF, external oscillator input. See figure 16. V _{DD} = 4.5 to 6.0 V	V _{SS}	_	0.20V _{DD}	٧
note 1.		n-channel transistor OFF, external oscillator input. See figure 16.	Vss	-	0.15V _{DD}	٧
TEST LOW-level input voltage	V	$V_{DD} = 4.5 \text{ to } 6.0 \text{ V}$	Vss	-	0.30V _{DD}	V
1251 LOW-lever input voitage	VILE		Vss	-	0.25V ₀₀	٧
Ports A, B, C, D, E and F HIGH-level output voltage (totem-pole output)	V _{OH1}	$I_{DM} = -50 \mu A,$ $V_{DD} = 4.5 \text{ to } 6.0 \text{ V}$	V _{DD} - 1.2	-	-	V
Ports A, B, C, D, E and F HIGH-level output voltage (totem-pole output)	V _{OH2}	lo _H = -10 μA	V _{DD} — 0.5	-	-	٧
Ports A, B, E and F HIGH-level	V _{OL1}	I _{OL} = 5 mA, V _{DD} = 4.5 to 6.0 V	-	-	1.5	٧
output voltage	V _{OL2}	I _{OL} = 1.0 mA, I _{OL} of other ports below 1 mA	_	-	0.5	V
Ports C and D LOW-level output	V _{OL3}	$i_{OL} = 15 \text{ mA},$ $V_{DD} = 4.5 \text{ to } 6.0 \text{ V}$	-	<u>-</u>	1.5	٧
voltage	V _{OL4}	I _{OL} = 2.0 mA, I _{OL} of other ports below 1 mA			0.5	٧
Port F, INTO, INT1, RES and START hysteresis voltage. See note 1.	V _{HY} s		-	0.1V _{DD}	-	V
Ports C, D and E, and F0 to F2 HIGH-level input current (open-drain output)	h _H ,	n-channel output transistor OFF (includes output transistor leakage current), V ₁ = 13.5 V	-	-	5.0	μΑ
Ports A and B, and F3 HIGH-level input current (open-drain output). See notes 1 and 5.	liH2	n-channel output transistor OFF (includes output transistor leakage current), V _I = V _{DD}	-		1.0	μΑ
RES HIGH-level input current	Іінз	VI = VDD	_	-	1.0	μА
OSC1 HIGH-level input current	l _{IH4}	V _I = V _{DD}	-	-	10	μА
Ports A, B, C, D, E and F LOW-level input current (open-drain output). See notes 1 and 5.	1111	n-channel output transistor OFF, V ₁ = Vss	-1.0	-	-	μА
Ports A, B, C, D, E and F LOW-level input current (totem-pole output). See notes 1 and 5.	l _{IL2}	n-channel output transistor OFF, V ₁ = Vss	-1.0	-0.5	-	mΑ

Parameter	Symbol Candition	01/1/		Rating	<u>-</u>	Unit
		Candition	min	typ	max	l our
RES LOW-level input current	lica	V _I = V _{SS}	-60	-25	_	
OSC1 LOW-level input current	l _{IL4}	V _I = V _{SS}	10	-	-	μА
	IDDOP1	$ f_{\text{osc}} = 4 \text{ MHz}, $	-	3	6	mA
	looors	$ \begin{aligned} f_{\text{OSC}} &= 4 \text{ MHz,} \\ \text{divide ratio} &= 1/2, \\ t_{\text{Cyc}} &= 1.9 \mu\text{s,} \\ V_{\text{DD}} &= 4.0 \text{ to } 6.0 \text{ V} \end{aligned} $	1	2	4	. mA
Operating current consumption. See note 4.	Іррорз	$\begin{array}{ll} f_{\text{OSC}} = 4 & \text{MHz}, \\ \text{divide ratio} = 1/32, \\ t_{\text{cyc}} = 30.5 & \mu\text{s}, \\ V_{\text{DD}} = 2.7 & \text{V} \end{array}$	-	0.3	1.0	mA
	DOOP4	$\begin{array}{ll} f_{\text{OSC}} = 400 \text{ kHz,} \\ \text{divide ratio} = 1/1, \\ t_{\text{Cyc}} = 10 \mu\text{s,} \\ V_{DD} = 4.0 \text{ to } 6.0 \text{ V} \end{array}$	-	0.5	2.0	mA
	DDOP5	$f_{OSC} = 400$ kHz, divide ratio = 1/1, $t_{CyC} = 10$ μ s, $V_{DD} = 2.7$ V	. 1	150	500	μА
	I _{DDST1}	HALT mode, 4.19 MHz clock, VDD = 6.0 V	_	0.7	1.5	mA
	I _{DDST2}	HALT mode, 4.19 MHz clock, V _{DD} = 2.7 V	1	150	500	μА
Standby current consumption. See note 4.	I _{DDST3}	HALT mode, 400 kHz clock, V _{DD} = 6.0 V	_	0.7	1.5	mA
	IDDST4	HALT mode, 400 kHz clock, V _{DO} = 2.7 V	_	100	300	μА
	DOSTS	HOLD mode, V _{DD} = 1.8 V	_	_	1	μА
	1DOST6	HOLD mode, V _{DD} = 6.0 V			10	μА
Ports A, B, C, D, E and F p-channel MOS output transistor resistance	R _{tru}	n-channel output transistor OFF, VDD = 5 V, V ₁ = Vss	8	12	30	kΩ
RES input pull-up resistance	Ru	V _{DD} = 5 V, V, = V _{SS}	100	-	400	kΩ

Notes

- 1. This value applies when the AC zero-crossing detector option is not selected.
- 2. Includes n-channel output transistor leakage current (transistor OFF)
- 3. Current dissipation values apply to microprocessor circuitry. They do not include currents associated with I/O port transistors.
- 4. These values do not include I/O port transistor currents.
- 5. Includes INTO, INTI and START

Serial interface

 V_{DD} = 4 to 6 V, V_{SS} = 0 V, T_{a} = -40 to 85 deg. C

D	A	0414	Rating			114
Parameter	Symbol	Condition	ion min		max	Unit
Input clock (SCK) period	tckcy1		8.0	_	_	μS
Output clock (SCK) period	tсксу2	See figure 19.	2.0 × t _{cyc}	-	_	μs
Input clock (SCK) LOW-level pulsewidth	t _{CKL1}	See figure 19. See note.	0.3	_	_	μ\$
Output clock (SCK) LOW-level pulsewidth	tckL2	See figure 19.	t _{cyc}		_	μs
Input clock (SCK) HIGH-level pulsewidth	tскн1	See figure 19. See note.	0.3	_ ·	_	μs
Output clock (SCK) HIGH-level pulsewidth	tскн2	See figure 19.	t _{cyc}	_	-	μѕ
SI data setup time	tick	Referenced to SCK	0.2	-		μs
SI data hold time	toki	rising edge. See figure 19.	0.2		_	μ\$
SO propagation delay	tcko	Referenced to \overline{SCK} falling edge. 1 $k\Omega$, 50 pF external load. See figure 19.	-	-	0.5	μs

Note

The pullup resistor values should be set so that t_{CKL1} and t_{CKH1} are greater than 0.3 $\mu s.$

AC zero-crossing detector input

 V_{DD} = 4.5 to 6.0 V, V_{SS} = 0 V, T_a = -40 to 85 deg. C

Parameter				Unit		
	Symbol	Condition	min	typ	max	Oill
Input frequency	fzı		40	_	1,000	Hz
Input voltage	Vzı	C = 1 μF	1.0	_	2.4	V _{p-p}
Detection error	VZA	60 Hz sinewave input		-	±100	m۷
HIGH-level input current	linz	VI = VDD	_	_	40	μА
LOW-level input current	lıçz	V _I = V _{SS}	-40	_	-	μΑ
Threshold voltage	V _I × A _{CM}		$0.3 \times V_{DD}$	-	$0.7 \times V_{DD}$	٧
LOW-level input threshold voltage	V ₁ × A _{CL}		-	V _t × A _{CM} -	-	٧

Note

Open-drain output with self-bias ON. See figures 21 and 22.

Self-exciting oscillator

 V_{DD} = 2.7 to 6.0 V, V_{ss} = 0 V, T_{a} = -40 to 85 deg. C unless noted otherwise

Parameter	D		Rating			11-5
	Symbol	Condition	min	typ	max	Unit
Crystal resonator frequency	foscx	See figure 14. See note 1.	-	4.19	_	MHz
Crystal oscillator start delay	t _{MXS}	See figure 15.		-	20	ms
Ceramic resonator frequency	foscor	See figure 14. See note 1.	392	400	408	kHz
Ceramic oscillator start delay	tmcfs	See figure 15.	_	-	10	ms
Instruction cycle time	tcyc	See note 1.	0.92	_	36	μs
External oscillator frequency	fxosc	See note 1.	0.39	-	4.33	MHz
External oscillator pulsewidth	twosccн	V _{DD} = 4.5 to 6.0 V. See figure 16.	70	_	_	ns
,	twosccL	See figure 16.	140		_	ns
External oscillator rise time	tosca	See figure 16.			30	ns
External oscillator fall time	toscr		_	_		ns

Notes

- The frequency is limited by the supply voltage, operating cycle time and frequency divider ratio.
 Oscillator constants are listed in table 3.

A/D converter

 V_{DD} = 5.0 V ±10%, V_{SS} = 0 V, T_{a} = -40 to 85 deg. C

Parameter	Symbol		Rating			Unit
		Condition	min	typ	max	Unit
Resolution			_	8	_	bit
Absolute precision			-	±1	±2	Isb
Zero-scale error	Ezs	AV + = V _{DD} , AV - = V _{SS}	_	_	±1	lsb
Full-scale error	E _{FS}	- 133	· -	_	±1	Isb
Conversion time	•	1/1 conversion speed = $26 \times t_{cyc}$ ($t_{cyc} = 0.92 \text{ to } 12 \mu s$)	24	_	312	μs
	†CAD	1/2 conversion speed = $51 \times t_{cyc}$ ($t_{cyc} = 0.92 \text{ to } 12 \mu s$)	40	_	612	μs
Input reference veltere	AV +		AV -	-	V _{DD}	٧
Input reference voltage	AV -	7	Vss	_	AV +	٧
Input reference current	IRIF	AV + = V _{DD} , AV - = V _{SS}	75	150	300	μΑ
Analog input voltage	V _{AI}		AV -	_	AV +	٧
Analog input current	IAI	Includes output OFF-state leakage current, V _{AI} = V _{DD}	-	_	1	μА
		VAI = VSS	_1	_		μΑ

Comparator

 V_{DD} = 5.0 V ±10%, V_{SS} = 0 V, T_a = -40 to 85 deg. C

Dan-at	Oumbal	Sumbal Condition		Rating					
Parameter	Symbol	Condition	min	typ	max	Unit			
Comparison precision	VCECON	AV + = V _{DD} , AV - = V _{SS}	-	±1	±2	lsb			
Threshold voltage	VTHCON		AV -	_	AV *	V			
Input voltage	Vincon		AV -	_	AV +	٧			
	AV +		AV -	_	V _{DD}	٧			
Input reference voltage	AV ~		Vss	_	AV +	٧			
Comparison time	•	1/1 comparison = 12 × t _{cyc} (t _{cyc} = 0.92 to 12 μs)	11	_	144	μs			
oompanson unie	tcc	1/2 comparison = $23 \times t_{cyc}$ (t_{cyc} = 0.92 to 12 μ s)	21	_	276	μs			

INSTRUCTION SET

Abbreviations

AC	A commutator
AC	Accumulator
ACt	Accumulator bit t
CF	Carry flag
CTL	Control register
DP	Data pointer
E	E register
hEn	Flag bit n

 $\begin{array}{lll} bFn & Flag \ bit \ n \\ GP(DP) & Pseudo \ port \ specified \ by \ DP \\ I_0 \ to \ I_3 & Immediate \ data \end{array}$

M Memory
M(DP) Memory addressed by DP
MSTEN Master interrupt enable fla

MSTEN Master interrupt enable flag
P(DPL) I/O port specified by DPL
PC Program counter

STACK Stack register

to, t₁

Immediate data which specifies the bit within the addressed nibble as follows.

t₁

t₀

Bit

0	0	Do
0	1	D ₁
1	0	D ₂
1	1	D ₃

Working registers
Zero flag
Indicates memory or register contents
Transfer in indicated direction
Add
Subtract
AND
OR
XOR

·								nstructi	on code			_		
Code	Description	Operation	FI	ag	D7	D6	05	D4	D3	D2	D1	DØ	Bytes	Cycles
			A.	stu mua:	lar						l			
ÇLA	Clear AC. See note 1.	AC ← 0	ZF		1	1	0	0	0	0	0	0	1	1
CLC	Clear CF	CF ← D		CF	1	1	1	0	0	0	Ô	1	1	1
STC	Set CF	CF ← 1		CF	1	1	1	1	0	0	0	1	1	1
CMA	Complement AC	AC ← (AC)	ZF		1	1	1	0	-	0	1	1	1	1
INC	Increment AC	AC ← (AC) + 1	ZF	CF	0	0	0	٥	1	1	1	a	1	1
DEC	Decrement AC	AC ← (AC) - 1	ZF	CF	0	0	٥	٥	1	1	-	1	1	1
RAL	Rotate AC left through CF	$AC0 \leftarrow (CF).AC_{n+1}$ $\leftarrow (AC_{n}). CF \leftarrow (AC_{3})$	Z۶	CF	0	0	0	0	0	0	0	1	1	1
TAE	Transfer AC to E	E ← (AC)			0	٥	٥	0	٥	٥	†	1	1	1
XAE	Exchange AC with E	(AC) ↔ (E)			0	0	0	0	1	1	0	1	1	1
			-	Meman										
INM	Increment M	$M(DP) \leftarrow [M(DP)] + 1$	ZF	CF	o	0	1	a	1	1	1	0	1	1
DEM	Decrement M	$M(DP) \leftarrow [M(DP)] - 1$	ZF	CF	0	O	1	a	1	1	1	1	1	1
SMB bit	Set M data bit	M(DP,B1B0) ← 1			٥	0	o	٥	1	0	B1	Ва	1	1
RMB bit	Reset M data bit	M(DP.B1B0) ← 0	ZF		0	0	1	0	1	0	B1	В0_	1	1
	Arithmetic and compare													
AD	Add M to AC	$AC \leftarrow (AC) + [M(DP)]$	ŻF	CF	0	1	1	0	0	С	0	٥	1	1
ADC	Add M to AC with CF	AC ← (AC) + [M(DP)] + (CF)	ZF	CF	٥	0	1	0	o	C	0	o .	1	1
DAA	Decimal adjust AC in addition	AC ← (AC) + 5	ZF		1	1	1	0	0	1_	1	0	1	1
DAS	Decimal adjust AC in subtraction	AC ← (AC) + 10	ZF		-	-	1	0	1	0	1	0	1	1
EXL	Exclusive OR M with AC	$AC \leftarrow (AC) \ \forall \ [M(DP)]$	ZF		1	1	1	1	0	1	0	1_	1	1
AND	AND M to AC	$AC \leftarrow (AC) \land [M(DP)]$	ZF		1	1	1	0	a	1	1	1_	1	1
OR	OR M with AC	$AC \leftarrow (AC) V [M(DP)]$	ZF		1	1	1	0	a	1	0	1	1	1
СМ	Compare AC with M. See table 1.	[M(DP)] + (AC) + 1	ΖF	CF	1	1	1	1	1	0	1	1	1	1
CI data	Compare AC with immediate data. See table 2.	J3 2 1 0 + (AC) + 1	ZF	CF	٥٥	0	1	0	1 3	1 12	0 1	0 (0	2	2
CLI data	Compare DPL with immediate data	(DPL) ∀ 3121110	ŻF		0	0	1	1	1 13	1 2	0 1	O IQ	2	2
			Loa	d and c	tors									
LI data	Load AC with immediate data. See note 1.	AC - 1312110	ZF		1	1	0	0	13	12	11	10	1	1
s	Store AC to M	M(DP) ← (AC)			0	0	0	0	0	٥	1	0	1	1
<u> </u>	Load AC from M	AC ← [M(DP)]	ZF		0	0	1	a	0	0	0	1_	1	1
XM data	Exchange AC with M, then modify DPH with immediate data. The zero flag is determined by comparing the data pointer high nibble with OM2M1M0.	(AC) [M(DP)] DPH ← (DPH) ∀ 0M2M1M0	ZF		1	a	1	a	a	M ₂	Μt	Mg	1	. 2
x	Exchange AC with M. The zero flag is determined by the contents of the data pointer high nibble.	(AC) harr [M(DP)]	ZF		1	0	1	0	0	0	Q	G	1	2
ХI	Exchange AC with M, then increment DPL. The zero flag is determined by the contents of the data pointer low nibble.	(AC) ↔[M(DP)] DPL ← (DPL) + 1	ZF		1	1	1	1	1	1	1	a	1	2
хо	Exchange AC with M, then decrement DPL. The zero flag is determined by the low nibble of the data pointer.	(AC) ↔[M(DP)] DPL ← (DPL) - 1	ZF		1	1	1	1	1	1	1	1	1	2
RTOL	Read table data from program ROM	AC.E ↔ROM (PCh. E.AC)			0	1	1	0	0	o	1	1	1	2

LC65102A, LC65104A

					Instruction code								Comina	
Code	Description	Operation		lag	D7	D6	05	D4	D3	D2	D1	DO	Bytes	Cycles
		D	ata poi	nter ma	nipulatio	Эл								
LDZ data	Load DPH with zero and DPL with immediate data, respectively.	DPH ← 0 DPL ← 13121110			1	0	0	0	13	12	11	lo	1	1
LHI data	Load DPR with immediate data	DPH ← 13121110			٥	1	0	0	13	12	11	lo .	1	1
IND	increment DPL	DPL ← (DPL) + 1	ZF		1	1	1	0	1	1	1	0	1	1
DED	Decrement DPL	DPL ← (DPL) ~ 1	ZF		1	1	1	0	1	1	1	1	1	1
TAL	Transfer AC to DPL	DPL ← (AC)			1	1	1	1	0	1	1	1	1	1
TLA	Transfer DP _L to AC	(AC) ← (DPL)	ZF		1	1	1	0	1	0	٥	1	1	1
ХАН	Exchange AC with DPH	(AC) ↔(DPH)			0	0	1	0	٥	0	1	1	1	1
			Wor	king reg	Ister		•							
XAt DAX 1AX SAX EAX	Exchange AC with working register bAt	(AC) ↔(bA0) (AC) ↔(bA1) (AC) ↔(bA2) (AC) ↔(bA3)			1 1 1 1	1 1 1 1	1 1 1 1	0000	t10011	1001	0000	0 0 0	1 1 1 1	1 1 1 1
XHa XH0 XH1	Exchange DPH with working register bHa	(DPH) ↔(bH0) (DPH) ↔(bH1)			1 1	1	1 1	1	1	a 0 1	0	0	1	1
XLa XLO XL1	Exchange DPL with working register bLa	(DPL) ↔(bL0) (DPL) ↔(bL1)			1	1	1	1	00	a 0 1	00	0	1	1
SRBA	Set register bank address	RBF ← Itio of SB			1	1	1	1	G	٥	1	G	1	1
			Bit	manipul	ation									
SFB flag	Set flag bit	bFn ← 1			0	1	0	1	83	B2	B1	80	1	1
RFB flag	Clear (Jag bi). The flags are organized in 16 × 4-bit nibbles from 0F0H to 0F9H to 3F0H to 3FFH. The zero (tag is determined by the contents of the specified nibble.	bFn ← O	ZF		0	0	О	1	В3	82	B1	80	1	1
			Jump	and sul	routine		.		· ·					
JMP addr	Jump in the current bank. The bank changes when a JMP instruction is followed by a BANK instruction.	PC ← PC11 (or PC11) P10P9P8P7 P10P10P10P3 P2P1P0			0 P7	1 P6	1 P5	0 P4	1 P3	P10 P2	Pg P1	Pa Pg	2	2
JPEA	Jump in the current page modified by E and AC	PC7 to 0 ← (E.AC)			1	1	1	1	1	0	1	0	1	1
CZP addr	Call subroutine in the zero page	STACK ← (PC) + 1 PC11 to 6. PC1 to 0 ← 0 PC5 to 2 ← P3P2P1P0			1	0	1	1	Рз	P2	P1	P0	1	1
CAL addr	Call subroutine in the zero bank	STACK ← (PC) + 2 PC11 to 0 ← 00 P10P9P8P7 P6P5P4P3 P2P1P0			1 P7	0 P6	1 P5	0 P4	1 P3	P10 P2	P9 P1	Pa Po	2	2
RT	Return from subroutine	PC ← (STACK)			٥	1	1	0	0	0	1	٥	1	1
RTI	Return from interrupt routine	PC ← (STACK) CF ZF ← CSF.ZSF	ZF	CF	0	a	1	0	0	0	1	0	1	1
BANK	Change bank	PC11 ← (PC11) GP(DP)			1	1	1	1	1	1	0	1	1	1
SB	Set bank	ABF ← 1110			0	1	1	٥	0	1	11	Ig	1	1
				Bra nch										
BAt addr	Branch on AC bit. Immediate data to and to is appended to BA, which is followed by the program counter branch address PO to P7	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if ACt = 1			0 P7	1 P6	1 P5	1 P4	0 P3	0 P2	t1 P1	to Po	2	2
BNA ₁ addr	Branch on no AC bit. Immediate data to and to is appended to BNA, which is followed by the program counter branch address Po to Pr.	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if ACt = 0			0 P7	0 P6	1 P5	1 P4	0 P3	0 P2	tı Pı	to Po	2	2

			instruction code									D-A	A	
Cade	Description	Operation Flag		3 0	D7 D6 O5 D4 D3 O2 D1 D					DO	Bytes	Cycles		
BMt addr	Branch on M bit. Immediate data to and to is appended to BM, which is followed by the program counter branch address Po to Pr.	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if [M(DP.t1t0)] = 1			0 P7	1 P6	1 P5	1 P4	0 P3	1 P2	tı Pı	to Po	. 2	2
BNMt addr	Branch on no M bit. Immediate data to and to is appended to BNM, which is followed by the program counter branch address Po to P7.	PC7 to 0 ← P7P6P5P4 P3P2P1P0 II [M(DP.11t0)] = 0			0 P7	0 P6	1 P5	1 P4	0 P3	1 P2	ts P1	to Po	2	2
BPt addr	Branch on port bit. Immediate data to and 11 is appended to BP, which is followed by the program counter branch address Po to P7.	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if [P(DPL1110)] = 1 or [GP(DP,1110)] = 1			0 P ₇	1 P6	1 P5	1 P4	1 P3	0 P2	11 P1	to Po	2	2
BNPt addr	Branch on no port bit. Immediate data to and to is appended to BNP, which is followed by the program counter branch address Po to P7.	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if [P(DPLt1t0)] = 0 or [GP(DP,t1t0)] = 0			0 P7	0 P6	1 P5	1 P4	1 P3	0 P2	t1 P1	to Po	2	2
BC addr	Branch on CF	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if CF = 1			0 P7	0 P6	1 P5	1 P4	1 P3	1 P2	1 P1	0 P0	2	2
BNC addr	Branch on no CF	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if CF = 0			0 P7	0 P6	1 P5	1 P4	1 P3	1 P2	1 P1	1 P0	2	2
BZ addr	Branch on ZF	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if ZF = 1			0 P7	1 P6	1 P5	1 P4	1 P3	1 P2	P ₁	a Po	2	2
8NZ addr	Branch on no ZF	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if ZF = 0			0 P7	0 P6	1 P5	1 P4	1 P3	1 P2	1 P;	O PQ	2	2
BF _n addr	Branch on flag bit. Immediate data ng, n1, n2 and n3 is appended to BF, which is followed by the program counter branch address P0 to P7.	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if bFn = 1			1 P7	1 P6	0 P5	1 P4	ng 23	n2 P2	ni Pi	no Po	2	2
8NF _n addr	Branch on no flag bit. Immediate data ng. ng. ng. and ng is appended to BNF, which is followed by the program counter branch address Pg to Pg.	PC7 to 0 ← P7P6P5P4 P3P2P1P0 if bFn = 0			1 P7	0 P6	0 P5	1 P4	п3 Р3	112 P2	n1 P1	ng Po	2	2
			In	put/out	put									
IP	Snput port to AC	AC ← [P(DPL)] or [GP(DP)]	ZF		0	0	0	0	1	1	٥	0	1	1
OP	Dulput AC to port	P(DPL) or GP(DP) ← (AC)			0	1	1	0	٥	٥	0	1	1	1
SPB bit	Set port bit. The contents of register E are lost.	P(DP _L B ₁ B ₀) or GP(DP,B ₁ B ₀) ← 1			0	٥	0	0	0	1	В1	BÇ	1	2
AP8 bit	Reset port bit. The contents of register E are lost.	P(DPL.B1B0) or GP(DP.B1B0) ← 0	ZF		0	0	1	0	0	1	81	8g	1	2
			Mi	scellane	юця									
SCTL bit	Set control register bit. See note 2.	CTL, 83828180 ← 1 or MSTEN ← 1			0	0	1 0	D 0	1 83	1 B2	0 B1	0 80	2	2
RCTL bit	Reset control register bit. See note 2	CTL. B3B2B1B0 ← 0 or MSTEN ← 0	ZF		0 1	0	1 0	0	1 83	1 82	0 81	0 Bo	2	2
HALT	Halt	Hatt, Hold			1	1	1	1	0	1	1	0	1	1
NOP	No operation	No operation			0	0	a	0	۵	0	0	0	1	1

Notes

- 1. After LI and CLA instructions are executed in succession, subsequent instructions are NOPs.
- 2. $B_3B_2B_1B_0 = 0000B$ to 1000B

Table 1. Magnitude conditions

Magnitude condition	CF	ZF .
[M(DP)] > (AC)	0	0
[M(DP)] = (AC)	1	1
[M(DP)] < (AC)	1	0

Table 2. Magnitude conditions

Magnitude condition	CF	Z 5-
1312110 > (AC)	0	0
$1_31_21_11_0 = (AC)$	1	1
3 2 1 0 < (AC)	1	0

USER MASK OPTIONS

The following user-specified mask options are available.

Oscillator Circuit

- Ceramic resonator
- · Crystal resonator
- External oscillator

System Clock Divide Ratio

The 1/1 or 1/32 frequency divider ratio mask options can be selected as the default ratios following a reset. The 1/1 ratio is used for the 390 kHz to 4330 kHz external clock input or the 400 kHz ceramic resonators. The 1/32 ratio is used for the 4.19 MHz crystal or the 4.0 MHz ceramic resonators.

Precautions

The evaluation chip has a default frequency divider ratio of 1/32 after reset, and the production chip, 1/1 after reset, unless 1/32 has been specified as a mask option. A four-step routine in the program header is used to change the frequency divider ratio.

Port C and D Output State Select

Port C and D outputs can all be cleared to 0 or set to 1 after a reset.

Watchdog Reset Circuit

A watchdog reset circuit generates interrupts which allows recovery from program runaways. The processor is programmed to reset the interrupt request flag at fixed intervals.

AC Zero-crossing Detector or Schmitt Trigger Input

The bidirectional port F bit (PF3) and interrupt request 0 (INT0) are multiplexed on PF3/INT0. This mask option allows the INT0 line to connect to either a Schmitt trigger input circuit or an AC zero-crossing detector circuit as shown in figure 1.

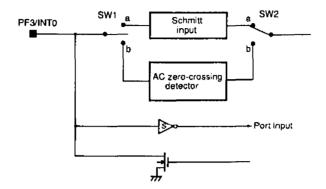


Figure 1. AC zero-crossing detector circuit

Open-drain or Totem-pole Output

I/O port output drivers can have either open-drain or totem-pole configurations as shown in figures 2 and 3. I/O port outputs should be tied LOW if open-drain output is selected.

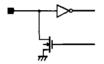


Figure 2. Open-drain output

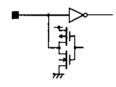


Figure 3. Totem-pole output

Option Code Specification

The client specifies mask options in an EPROM together with the program code. A cross-assembler is available for the LC65102A and LC65104A that allows these options to be specified interactively. The address map shown in figure 4 should be used if the EPROM is programmed manually, resulting in the same format generated by the cross-assembler. Either 2764 or 27128 EPROMs can be used.

- No products described or contained herein are intended for use in surgical implants, life-support systems, aerospace equipment, nuclear power control systems, vehicles, disaster/crime-prevention equipment and the like, the failure of which may directly or indirectly cause injury, death or property loss.
- Anyone purchasing any products described or contained herein for an above-mentioned use shall:
 ① Accept full responsibility and indemnify and defend SANYO ELECTRIC CO., LTD., its affiliates, subsidiaries and distributors and all their officers and employees, jointly and severally, against any and all claims and litigation and all damages, cost and expenses associated with such use:
 - ② Not impose any responsibility for any fault or negligence which may be cited in any such claim or litigation on SANYO ELECTRIC CO., LTD., its affiliates, subsidiaries and distributors or any of their officers and employees jointly or severally.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. SANYO believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

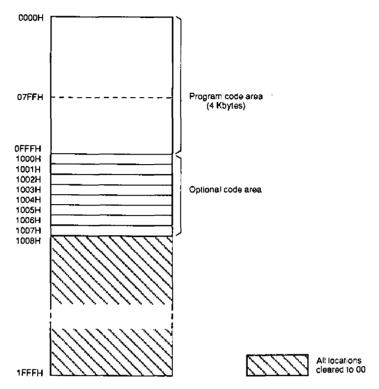


Figure 4. EPROM address map

Note

The memory locations 800H to FFFH of LC65102 should be cleared to 00 during development.

Option codes

Figures 5 to 12 show how option codes are related to their corresponding functions.

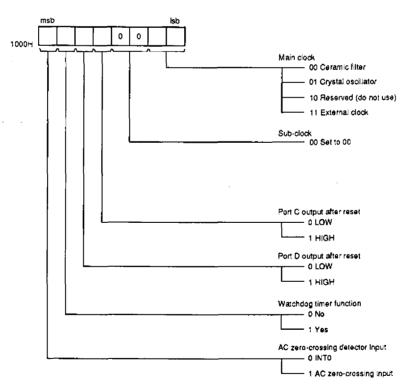


Figure 5. Bit allocation

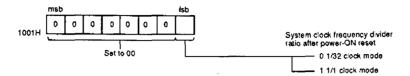


Figure 6. 1001H

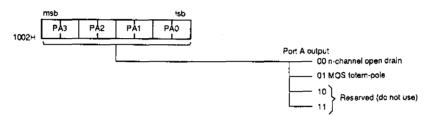


Figure 7. 1002H

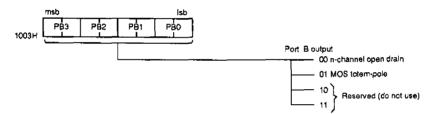


Figure 8. 1003H

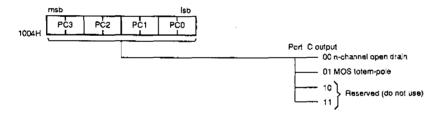


Figure 9. 1004H

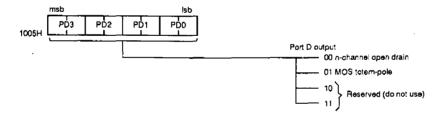


Figure 10. 1005H

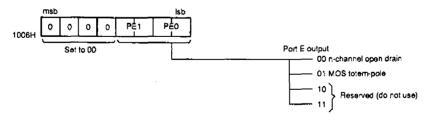


Figure 11. 1006H

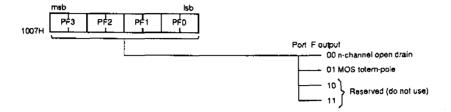


Figure 12. 1007H

DEVELOPMENT SYSTEM

The development system available for the LC65102A and LC65104A comprises the following aids.

- LC65104A/LC65102A User's Manual
- EVA850/800-LC651XX/2XX/3XX/4XX Development Tools Manual
- Development tools

Development Tools

The development tools comprise an MS-DOS based cross-assembler (LC65S.EXE) for program development, an evaluation chip (LC65999), piggyback connector (LC65PG10X), and emulator (EVA-800 or EVA-850 main unit and evaluation chip board) for program evaluation as shown in figure 13.

Notes

- 1. MS-DOS is a trademark of Microsoft Corporation.
- 2. Upgrades of the EVA-800 or EVA-850 emulators are indicated by an alphabetic character appended to the emulator name.

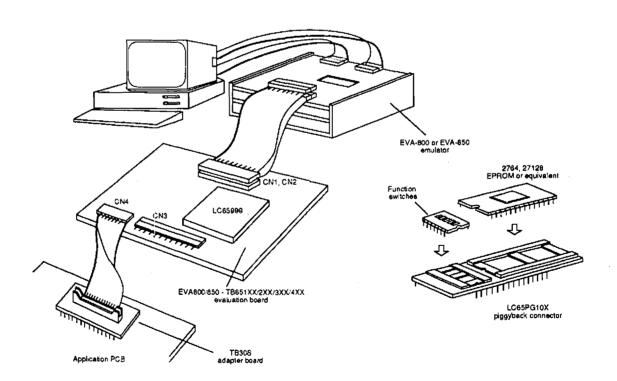


Figure 13. Development system components

Evaluation Notes

The following guidelines should be observed when evaluating programs for the LC65102A/LC65104A using the LC65999 and the LC65PG10X.

Selection

RAM capacity

The RC and RC2 pins are used to select RAM capacity. The LC65102A has a 128×4 -bit RAM, and the LC65104A, a 256×4 -bit RAM. The evaluation chip can have either.

Stack nesting

The STC pin is used to select the number of stack nesting levels. The LC65102A and LC65104A support eight levels of nesting.

Ports C, D, E and F output configuration

Ports C, D, E and F have 15 V breakdown-voltage, medium-current drive I/O circuits. The C/FLSEL pin of the evaluation tool is used to select the I/O configuration of ports C and D which can be either p-channel, high voltage or n-channel. Port F output drivers PF0 to PF2 have normal breakdown voltage I/O circuits when masked for the totem-pole configuration, and output driver PF3, in either totem-pole or open-drain configurations.

Mask options

Oscillator circult

The resonator should be connected to OSC1 and OSC2. The oscillator type is selected by setting jumpers on the evaluation board. The simulation chip is identical to a volume-produced chip.

Port C and D after reset

The four bits of port C and D can be specified to go either all HIGH or all LOW following reset. The CHL pin is used to select the level for port C, and the DHL pin to select the level for port D.

Watchdog reset function

Specify whether to implement the watchdog reset function using the timer or not. The WDC pin is used to select or deselect the watchdog reset function.

AC zero-crossing detector

Specify whether or not to implement the AC zero-crossing detector input circuit on PF3/INTO.

The ACZ/INTO pin is used to select or deselect the AC zero-crossing detector.

Open-drain or totem-pole output

Specify either totem-pole or open-drain configuration for each output. All evaluation chip ports have n-channel, open-drain outputs. Pull-up resistors of $10 \text{ k}\Omega$ should be connected to the ports on the simulation and evaluation chips.

Pull-up resistor configuration

The evaluation and simulation chips have open-drain outputs which require external pull-up resistors. When the outputs are LOW, there is continuous current drain through the pull-up resistors. No external pull-up resistors are required and only leakage currents flow in the output transistors if the totem-pole output option is selected for volume-produced chips.

Oscillator circuit

The circuit design and characteristics for evaluation chips differ from those for volume-produced chips. As a result, wiring capacitance may lead to unstable oscillation.

The external components should be trimmed as necessary to obtain stable oscillation.

Operating requirements

Detailed evaluation of the frequency characteristics and current consumption should be carried out using engineering samples ES and commercial samples CS.

The supply voltage should be restricted within the range of the EPROM and connected LSIs. The supply should be $5~V~\pm 5\%$ to ensure that rated voltages are not exceeded. However, this makes it impossible to evaluate circuit operation over the entire supply voltage range of volume-produced chips.

The guaranteed ambient operating temperature range is 10 to 40 deg. C.

The LC65102A has a 2 Kbyte ROM, allowing jumps to any address using the JMP instruction. The LC65104A has a 4 Kbyte ROM, allowing jumps to any address using either a single JMP instruction or a BANK followed by JMP instruction.

External ROM up to 8 Kbytes can be used, allowing jumps to any address using either an SB followed by JMP instruction, or a single JMP instruction. Ensure that the program does not exceed 2 Kbytes for the LC65102A or 4 Kbytes for the LC65104A.

DESIGN NOTES

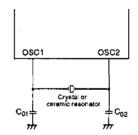


Figure 14. Oscillator circuit

Table 3. Guaranteed oscillator constants

Resonator	Vendor	Part description	C ₀₁	COS	Unit
4.194304 MHz crystal	Kinseki	HC-49/U C _L = 13.2 pF	18	18	pF
4.0 MHz ceramic resonator	B.d	GSA4.00MG	33	33	
	Murata	CST4.00MGW. See note 3.	None	None	
	16	KBR-4.0MS	33	33	pF
	Kyocera	KBR-4.0MES. See note 3.	None	None	
	Fujicera	POF-4.00	33	33	
	Murata	CSB400P	330	330	
400 kHz ceramic resonator	Kyocera	KBR-400B	330	330	pF
Γ	Fujicera	POE-400	330	330	

Notes

- 1. Values of CO1 and CO2 (including wiring capacitance when installed) should be within ±10% of specifications.
- 2. CL is the resonator's built-in capacitor value
- 3. Three-pin resonator with built-in capacitor

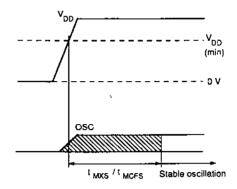


Figure 15. Oscillator start delay

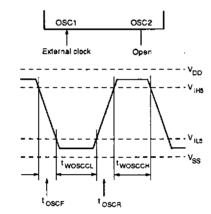


Figure 16. External clock input timing

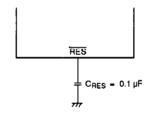


Figure 17. Reset circuit

Note

The reset time is 10 to 100 ms when $C_{RES} = 0.1 \, \mu\text{F}$, assuming a power supply with zero rise time. C_{RES} should be selected so that the reset time is greater than the main oscillator start delay if the power supply rise time is excessive.

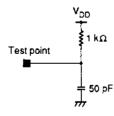


Figure 18. Serial output load

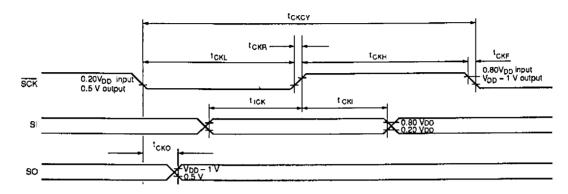


Figure 19. Serial I/O timing

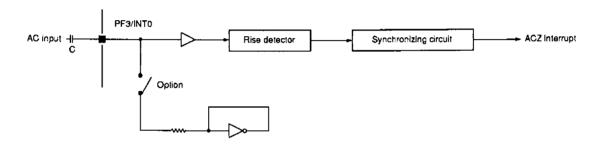


Figure 20. AC zero-crossing detector

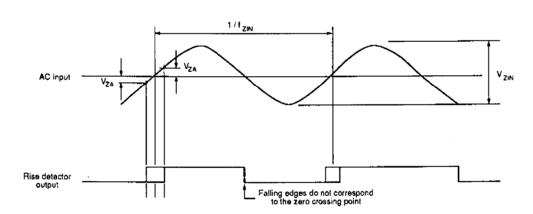


Figure 21. AC zero-crossing timing

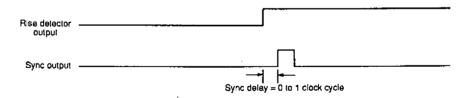


Figure 22. AC zero-crossing sync delay

PROGRAMMING NOTES

The following guidelines should be observed when developing programs for the LC65102A/LC65104A.

System Clock Functions

System clock mode

The LC65102A/LC65104A provides three software-selectable clock modes. Clock modes cannot be changed if the 1/1 frequency divider ratio after reset option is selected.

- Clock 1/1 mode ($t_{cyc} = 0.95 \mu s$)
- Clock 1/2 mode ($t_{eye} = 1.90 \mu s$)
- Clock $1/32 \text{ mode } (t_{\text{eye}} = 30.6 \text{ } \mu\text{s})$

Notes

- 1. These values apply for a main clock frequency of 4.19 MHz.
- 2. A clock signal must be supplied at system startup.

System clock switching mode

The system clock source is selected by the clock mode flags (CMF), a two-bit location in the control register. The default system clock frequency divider ratio after reset is 1/32.

Clock mode flags (CMF)	Clock divide ratio
0	Main clock × 1/32 (default on reset)
1	Main clock × 1/1. See note 3.
2	Main cłock × 1/2
3	Do not use

Notes

- 1. Ensure that the clock oscillator is stable or an external clock signal is applied before changing modes.
- 2. The mode change occurs at a maximum of 64 main clock cycles after writing to the clock mode flag. A delay should be allowed between a mode change operation and a HALT instruction.
- 3. The system clock frequency divider ratio cannot be changed if this ratio is selected as the power-ON default.

Standby Modes

HALT mode

The HALT command can be used to override the watchdog timer, which halts operation, whether the WG2 and WG3 flags are set to 1 or not. This enables release by either a HIGH on PB3/START or the interrupt release signal.

Entry

Issuing the HALT instruction when the standby control register SLPF flag is 0 invokes HALT mode. However, it is equivalent to a NOP (no operation) instruction under the following exit conditions.

- Rese
- The PB3/START line goes HIGH while WG2 = 1.
- The interrupt release signal goes active while WG3 = 1.
- The 14-bit frequency divider overflows. Normal operation commences after a maximum of 0.5 seconds if a 4.19 MHz clock is used.

HOLD mode

Entry

Issuing the HALT instruction when the SLPF flag is 1 invokes HOLD mode.

A single NOP instruction is issued prior to entering HOLD mode. The WG1 flag must be set to 1 before entering HOLD mode to enable release by a HIGH on PB3/START. The timebase clock source should be set to 1/128 of the oscillator clock.

Exit

HOLD mode is exit when one of the following conditions occur.

- Reset
- The PB3/START line goes HIGH while WG1 = 1.

Watchdog Timer

The watchdog timer is used to detect program runaway and generate a reset. The following guidelines should be observed.

- Write a routine in the program that resets the TBF flag periodically before a timer overflow occurs. It should be written so that the instruction that resets the TBF flag is not issued at the same time as the timeout interrupt request signal is generated.
- Select a timer divide ratio
- If the timebase interrupt request flag TBF is 1 prior to invoking HALT mode, a timer overflow will initiate a watchdog reset and an exit from HALT mode. To prevent a watchdog reset when HALT mode is exit, either reset the TBF flag immediately before issuing the HALT instruction or set the TBF flag and the WG3 flag (interrupt-invoked HALT exit).

Interrupts

The following guidelines should be observed for interrupts.

- Interrupts are enabled using control register bit 5.
- Each of the 5 interrupt vectors is allocated its own enable flag. The desired interrupts can be enabled by setting the appropriate flags. It is not possible to access multiple bits simultaneously using the SCTL0 to 7 instructions. All flags are cleared when a reset occurs.
- · Flags can be cleared by issuing a RCTL instruction for each flag.
- Invoking HOLD mode disables all flags. They should be enabled after exiting HOLD mode.
- The interrupt flags are configured as a pseudo port. Individual flags are selected by setting the corresponding accumulator bits to 1 and copying them to the interrupt request register. When a BANK instruction is issued after an IP instruction, the flags are cleared. When a BANK instruction is issued after an OP instruction, the selected flag is set.
- · All interrupt flags except timer 1 flag are cleared to 0 after a reset.
- All interrupt flags are cleared to 0 after HOLD mode is invoked.
- The serial I/O flag SIOF is cleared to 0 when serial data transfer begins.
- Each interrupt flag including the interrupt enable flag should be set individually following an interrupt.
- A BANK instruction followed by a SPB or RPB instruction does not access the interrupt request register.